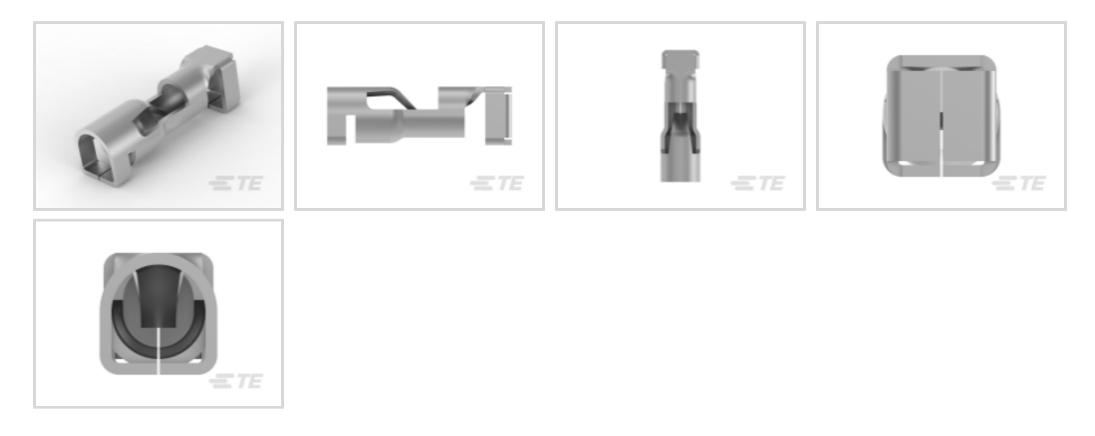
# 2834012-3 - ACTIVE

### Buchanan WireMate | BUCHANAN WireMate Slim Poke-In

TE Internal #: 2834012-3 Wire-to-Board, Printed Circuit Board, 3.1 mm [.122 in] Height, Surface Mount, 16 – 20 AWG, Power, BUCHANAN WireMate Slim Poke-In, Poke-In Connectors

#### View on TE.com >

#### Connectors > Lighting Connectors > Poke-In Connectors



Connector System: Wire-to-Board

Connector & Contact Terminates To: Printed Circuit Board

Connector Height: 3.1 mm [.122 in ]

Termination Method to PCB: Surface Mount

Wire Size: 16 – 20 AWG

## Features



### Product Type Features

Product Line	Poke-In
Connector System	Wire-to-Board
Connector & Contact Terminates To	Printed Circuit Board
Electrical Characteristics	
Operating Voltage	300 VAC
Body Features	
Primary Product Color	Natural
Contact Features	
Contact Underplating Material	Nickel
Contact Mating Area Plating Material	Tin (Sn)
PCB Contact Termination Area Plating Material	Tin-Lead
PCB Contact Termination Area Plating Material Finish	Matte
Contact Current Rating (Max)	16 A

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#### **Termination Features**

Termination Method to PCB	Surface Mount
Dimensions	
Compatible Insulation Diameter Range	2.1 mm[.083 in]
Connector Height	3.1 mm[.122 in]
Wire Size	16 – 20 AWG
Usage Conditions	
Operating Temperature Range	-40 – 125 °C[-40 – 257 °F]
Operation/Application	
Circuit Application	Power
Industry Standards	
Compatible With Agency/Standards Products	UL
UL Flammability Rating	UL 94V-0
Compatible With Approved Standards Products	UL 1977, UL E28476
Packaging Features	
Packaging Method	Reel/Carton

## Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 245°C

Solder Process Capability

Reflow solder capable to 245°C

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent

Wire-to-Board, Printed Circuit Board, 3.1 mm [.122 in] Height, Surface Mount, 16 – 20 AWG, Power, BUCHANAN WireMate Slim Poke-In, Poke-In Connectors



chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

## **Compatible Parts**



# Also in the Series | BUCHANAN WireMate Slim Poke-In



Poke-In Connectors(5)

## Customers Also Bought



Wire-to-Board, Printed Circuit Board, 3.1 mm [.122 in] Height, Surface Mount, 16 – 20 AWG, Power, BUCHANAN WireMate Slim Poke-In, Poke-In Connectors







## Documents

Product Drawings SLIM CONTACT FOR WIRE 16-20AWG

English

CAD Files

3D PDF

3D

Customer View Model ENG\_CVM\_CVM\_2834012-3\_A.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_2834012-3\_A.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_CVM\_2834012-3\_A.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages Slim Wire-to-Board flyer English

Slim Wire-to-Board flyer

English

**BUCHANAN WireMate Connectors Brochure** 

**BUCHANAN WireMate Connectors Brochure** 

English

Wire-to-Board, Printed Circuit Board, 3.1 mm [.122 in] Height, Surface Mount, 16 – 20 AWG, Power, BUCHANAN WireMate Slim Poke-In, Poke-In Connectors



Product Specifications Application Specification English Instruction Sheets Instruction Sheet (non U.S.) English Agency Approvals UL Report English